

Technical Data Sheet

EVAF500G non-silicone thermal gap pads are manufactured from highly Engineered resins. EVAF500G non-silicone thermal gap pads will not create circuit failure as they contain no siloxane volatilization, therefore will not promote silicone oil seeping. EVAF500G Non-Silicone thermal gap pads have excellent tensile strength and wear resistance. EverTherm Non-Silicone pads exhibit low outgassing, excellent tensile and wear resistance.



Applications

- ✓ Power battery pack
- ✓ Vehicle navigator
- ✓ Optical precision equipment
- ✓ Camera equipment
- ✓ Notebook computer
- ✓ Mobile and communication equipment
- ✓ Automotive engine control equipment
- ✓ High end industrial control and medical electronics



EVAF500G NON-SILICONE

Color	White	Visual
Thickness	0.5 - 5.0mm	ASTM D374
Specific Gravity	3.0g/cm ³	ASTM D792
Thermal Conductivity	3.50 W/mK	ASTM D5470
Hardness(shore oo)	45-80	ASTM D2240
Elongation	70%	ASTM D412
Tensile Strength	50psi	ASTM D412
Dielectric Breakdown Voltage	>8KV/AC/mm	ASTM D149
Flammability Rating	94 V-0	UL 94
Volume Resistivity	1013Ω.cm	ASTM D257
Operating Temperature	-40 - 130°C	---
Thermal Resistance(1mm,@40psi)	0.58°C*in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	30%	---
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

CR Technology, Inc

📍 55 Chase St. Methuen,
Massachusetts 01844

✉ sales@crtechinc.com

☎ 978.681.5300

Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.